Amendments to the Claims:

Please amend the claims to read as follows. This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1. (Canceled)

2. (Canceled)

3. (Canceled)

4. (Canceled)

5. (Canceled)

6. (Canceled)

7. (Canceled)

8. (Canceled)

9. (Currently amended) The carrier of claim 17[[8]] further comprising a fiber clip disposed on the fiber guide to secure an optical fiber extending from the laser module to the fiber guide.

10. (Canceled)

11. (Currently amended) The carrier of claim 18[[10]] further comprising a wire clip disposed on the wire guide for attaching at least one wire extending from the electronics module to the wire guide.

12. (Canceled)

13. (Canceled)

14. (Canceled)

15. (Original) A carrier for attachment of a laser module to a circuit board, the laser module having a plurality of leads extending therefrom, the carrier comprising:

a frame having a first side, a second side and a third side in a C-shaped configuration, at least one of the sides having a first surface, at least one of the sides having a second surface, and at least one of the sides having an opening to receive a board fastener, the first and second surfaces being separated by a predetermined distance so that the leads of the laser module are positioned substantially along a surface of the circuit board when the laser module is secured to the carrier and the carrier is secured to the circuit board;

a first plurality of alignment posts disposed on the first surfaces;

a second plurality of alignment posts disposed on the second surfaces;

a capture clip disposed on one of the sides to secure the laser module to the frame; and

a fiber guide extending from one of the sides.

16. (Original) The carrier of claim 15 further comprising a fiber clip disposed on the fiber guide to secure an optical fiber extending from the laser module to the fiber guide.

17. (New) A carrier for alignment and attachment of a laser module to a circuit board, the laser module having a plurality of leads extending therefrom, the carrier comprising:

a frame having a plurality of sides defining a region to receive the laser module, the frame having a gap between two of the sides for passage of the leads from the laser module, at least one of the sides having a first surface configured to maintain contact with a surface of the laser module when the laser module is secured to the frame, at least one of the sides having a second surface configured to maintain contact with a surface of the circuit board when the carrier is secured to the circuit board, the first and second surfaces of the sides being separated by a predetermined distance to position all the leads substantially in contact with the surface of the circuit board;

a first alignment guide disposed on the frame to align the laser module to the carrier; and

a fiber guide extending from one of the sides opposite the region to receive the laser module.

18. (New) A carrier for alignment and attachment of an electronics module to a circuit board, the electronics module having a plurality of leads extending therefrom, the carrier comprising:

a frame having a plurality of sides defining a region to receive the electronics module, the frame having a gap between two of the sides for passage of the leads from the electronics module, at least one of the sides having a first surface configured to maintain contact with a surface of the electronics module when the electronics module is secured to the frame, at least one of the sides having a second surface configured to maintain contact with a surface of the circuit board when the carrier is secured to the circuit board, the first and second surfaces of the sides being separated by a predetermined distance to position all the leads substantially in contact with the surface of the circuit board;

a first alignment guide disposed on the frame to align the electronics module to the carrier; and

a wire guide extending from one of the sides opposite the region to receive the electronics module.